Processing, Materials, and Integration of Damascene and 3D Interconnects

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Preface

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## Table of Contents

**Preface**

Integration and Frequency Dependent Parametric Modeling of Through Silicon via Involved in High Density 3D Chip Stacking


Modeling of Electromigration Induced Contact Resistance Reduction of Cu-Cu Bonded Interface

R. I. Made, C. Gan, and C. Tan

Leakage Current Analysis of Lateral p+/n Ge Based Diode Activated at Low Temperature for Three-Dimensional Integrated Circuit (3D-ICs)

W. Jung, J. Park, D. Kuzum, W. Kim, S. Wong, and K. C. Saraswat

Use of Polymer Liners for 3D-WLP TSVs: Process, Reliability and Cost

D. Sabuncuoglu Tezcan, N. Pham, B. Majeed, Y. Civale, and E. Beyne

From 2D Lithography to 3D Patterning

H. W. van Zeijl, J. Wei, C. Shen, T. M. Verhaar, and P. Sarro

3D Hybrid Integration Technology for Opto-Electronic Hetero-Integrated Systems

K. Lee, T. Fukushima, T. Tanaka, and M. Koyanagi

High-Performance 3D Interconnects Based on Electrochemical Etch and Liquid Metal Fill

H. Hedler, T. Scheiter, and M. Schieber

CMOS Compatible Anodization Process for Low Cost High Density Capacitors

M. Detalle, M. Rakowski, G. Potoms, A. Mercha, M. de Potter de ten Broeck, A. Phommahaxay, D. Sabuncuoglu Tezcan, and P. Soussan

Ultra Low-k Materials: Challenges of Scaling

L. Zhao, M. Baklanov, M. Pantouvaki, Z. Tőkei, and G. Beyer

Ultra-Low Temperature Deposition of Copper Seed Layers by PEALD

J. Mao, E. Eisenbraun, V. Omarjee, A. Korolev, C. Lansalot, and C. Dussarrat
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